JSTOMER	:			
AMPLE CODE	: SH240320T-00	62-L-Q		
ASS PRODUCTION CODE	PH240320T-00	62-L-Q		
AMPLE VERSION	. 02			
CIFICATIONS EDITION . 007				
RAWING NO. (Ver.)	: LMD-PH24032	LMD-PH240320T-062-L-Q (Ver.003)		
ACKAGING NO. (Ver.)	PKG-PH24032	20T-062-L-Q (Ver:001)		
	Γ	Date:		
Approved	Checked	Date: Designer		

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History of Version

Date (mm / dd / yyyy)	Ver.	Edi.	Description	Page	Design by
08/03/2012	01	001	New Drawing	-	Howard
08/20/2012	01	002	Modify TFT Size	Appendix	Howard
09/14/2012	01	003	New Sample Modify Interface Pin Description	- 11,12	Howard
12/12/2012	02	004	Second Sample Modify Optical Characteristics Modify Drawing	- 6 Appendix	Howard
03/24/2014	02	005	Modify Contrast Ratio	6	Howard
08/24/2014	02	006	Show Backlight Life Time	9	劉進
08/27/2015	02	007	Modify Backlight Life Time	9	劉進
	X				

Total: 32 Page



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- 1.3 Absolute Maximum Ratings
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Appendix: LCM Drawing

Packaging

Note: For detailed information please refer to IC data sheet: ILITEK - ILI9341



1. SPECIFICATIONS

1.1 Features

Main LCD Panel

Į.	
Item	Standard Value
Display Type	240 * (R · G · B) * 320 Dots
LCD Type	a-Si TFT , Normally White TN , Transmissive
Screen size(inch)	2.4 (Diagonal)
Viewing Direction	12 O'clock
Color configuration	R.G.B. vertical stripe
Backlight	White LED
Interface	8 Bit Interface for i80system
Driver IC	ILI9341
	THIS PRODUCT CONFORMS THE ROHS OF PTC
ROHS	Detail information please refer website :
	http://www.powertip.com.tw/news.php?area_id_view=1085560481/

1.2 Mechanical Specifications

Item	Standard Value	Unit
Outline Dimension	42.32 (W) * 60.06 (L) * 2.4 (H)	mm

LCD Panel

Item	Standard Value		
Viewing Area	37.72 (W) * 49.96(L)	mm	
Active Area	36.72(W) * 48.96(L)	mm	

Note: For detailed information please refer to LCM drawing



1.3 Absolute Maximum Ratings

Module

Item	Symbol	Condition	Min.	Max.	Unit
System Dower Supply Voltage	VDD -		-0.3	4.6	V
System Power Supply Voltage	VGH-VGL	GND	0	+32	V
Logic Input Voltage	VIN	-	-0.3	VDD+0.3	٧
Operating Temperature	TOP	-	-20	70	°C
Storage Temperature	TST	-	-30	80	°C

1.4 DC Electrical Characteristics

Module GND = 0V, Ta = $25^{\circ}C$

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Power Supply Voltage	VDD	4 -	-	2.8	-	٧
Input High Voltage	V _{IH}	<u> </u>	0.7*VDD	-	VDD	٧
Input Low Voltage	VIL	-	GND	-	0.3*VDD	٧
Output High Voltage	Vон	IOH=-0.1mA	0.8*VDD	-	VDD	٧
Output Low Voltage	V _{OL}	IOL=0.1mA	GND	-	0.2*VDD	٧
Supply Current	IDD	VDD = 2.8V Pattern= black *1	-	8	15	mA

Note 1: Maximum current display





1.5 Optical Characteristics

TFT LCD panel

VDD= 2.8 V, Ta=25°C

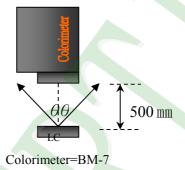
-								
Item		Symbol	Condition	Min.	Тур.	Max.	unit	
Response time	Rise Fall	Tr+Tf	Ta = 25°C θX, θY = 0•	-	25	38	ms	Note2
	Тор	θΥ+		-	60	-		
Viouing angle	Bottom	θΥ-	CR ≥ 10	-	60	-	Dog	
Viewing angle	Left	θX-	CR 2 10	-	60	-	Deg.	Note4
	Right	θX+		-	60	-		
Contrast rati	0	CR	Ta = 25°C θX , θY = 0•	500	600	-	-	Note3
	White	Χ		0.22	0.27	0.32		
	vviile	Υ		0.23	0.28	0.33		
0 1 1015	Red	Х		0.51	0.56	0.61		
Color of CIE Coordinate		Υ	$Ta = 25^{\circ}C$	0.29	0.34	0.39		Note1
(With B/L & T/P)	Green	X	θX , $\theta Y = 0$ •	0.27	0.32	0.37	_	Note
(VIIII D/L & 1/1)	Green	Υ		0.54	0.59	0.64		
	Blue	X		0.09	0.14	0.19		
	Diue	Υ		0.01	0.06	0.11		
Average Brightness								
Pattern=white display		IV	IF=60 mA	110	120	-	cd/m ²	Note1
(With B/L)								
Uniformity (With B/L)		∆B	IF=60 mA	80	-	-	%	Note1



Note1:

- *1: \(\triangle B = B(min) / B(max) * 100%
- *2 : Measurement Condition for Optical Characteristics:
 - a : Environment: 25°C±5°C / 60±20%R.H , no wind , dark room below 10 Lux at typical lamp current and typical operating frequency.
 - b : Measurement Distance: $500 \pm 50 \text{ mm}$, $(\theta = 0^{\circ})$
 - c: Equipment: TOPCON BM-7 fast, (field 1°), after 10 minutes operation.
 - d: The uncertainty of the C.I.E coordinate measurement ±0.01, Average Brightness ± 4%





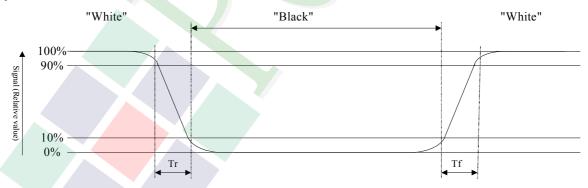
To be measured at the center area of panel with a viewing cone of 1• by Topcon luminance meter BM-7, after 10 minutes operation (module)

Note2: Definition of response time:

The output signals of photo detector are measured when the input signals are changed from "black" to "white" (falling time) and from "white" to "black" (rising time), respectively. The response time is defined as the time interval between the 10% and 90% of Amplitudes.

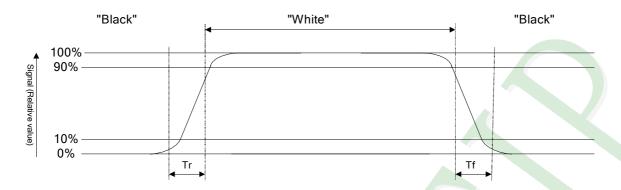
Refer to figure as below:

Normally White





Normally Black



Note3: Definition of contrast ratio:

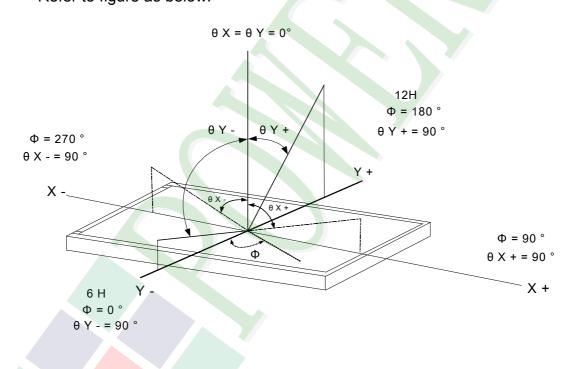
Contrast ratio is calculated with the following formula

Photo detector output when LCD is at "White" state

Contrast ratio (CR) =

Photo detector output when LCD is at "Black" state

Note4: Definition of viewing angle: Refer to figure as below:





1.6 Backlight & LED Characteristics

LCD Module with LED Backlight

Maximum Ratings

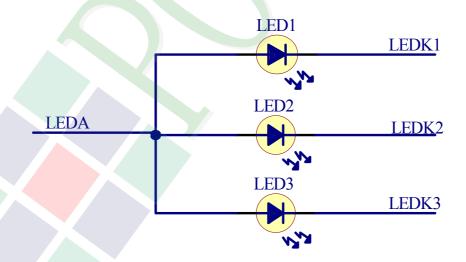
Item	Symbol	Conditions	Min.	Max.	Unit
Forward Current	IF	Ta =25°ℂ	- 🔥	75	mA
Reverse Voltage	VR	Ta =25°ℂ	_	4	V

Electrical / Optical Characteristics

Item	Symbol	Conditions	Min.	Тур.	Max.	Unit
Forward Voltage	VF		-	3.2	3.5	V
Average Brightness (without LCD)	IV	IF= 60 mA	2500	2800	_	cd/m ²
Color of CIE Coordinate*1	X		-	0.27	-	*2
(Without LCD)	Y		-	0.27	-	2
Color			White			

*1 : This value will be changed while mass production.

*2 : △B=B(min) / B(max) *100% B/L Internal Circuit Diagram



Other Description

Item	Conditions	Description
Life Time	Ta =25°ℂ	20000 hrs
Life Tillie	IF= 20mA	20000 1115



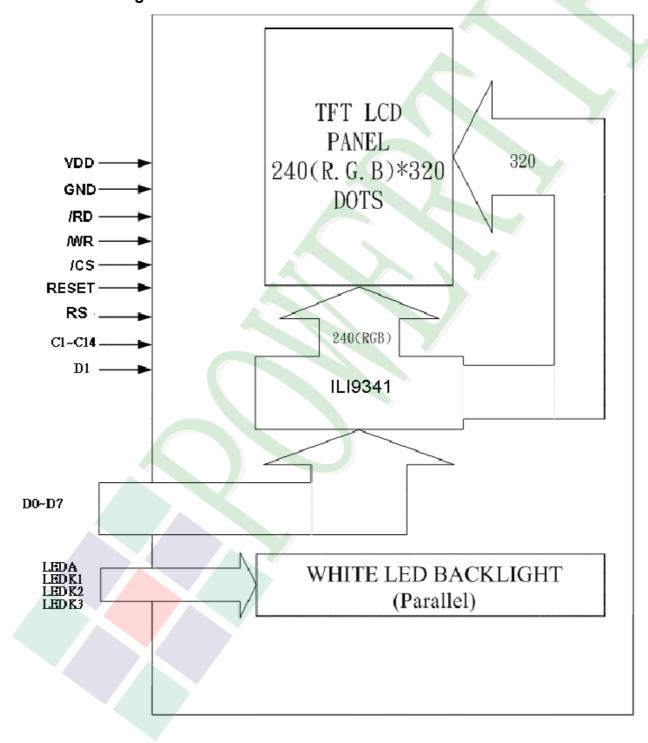
2. MODULE STRUCTURE

2.1 Counter Drawing

2.1.1 LCM Mechanical Diagram

* See Appendix

2.1.2 Block Diagram





2.2 Interface Pin Description

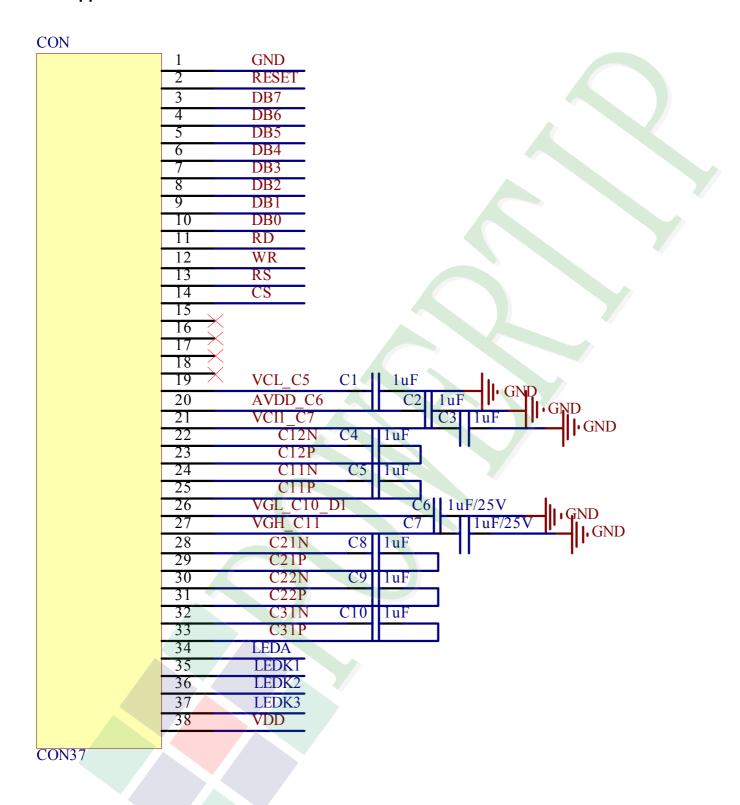
Pin No.	Symbol	Function
1	GND	System Ground.(0V)
2	RESET	This signal will reset the device and must be applied to properly initialize the chip. Signal is active low.
3	DB7	Bi-directional data bus.
4	DB6	Bi-directional data bus.
5	DB5	Bi-directional data bus.
6	DB4	Bi-directional data bus.
7	DB3	Bi-directional data bus.
8	DB2	Bi-directional data bus.
9	DB1	Bi-directional data bus.
10	DB0	Bi-directional data bus.
11	RD	Serves as a read signal and MCU read data at the rising edge.
12	WR	Serves as a write signal and writes data at the rising edge.
13	RS	When RS = '1', data is selected. When RS = '0', command is selected.
14	/CS	Chip select input pin ("Low" enable).
15	VDD_C1	Not Connect.
16	VCOMH_C2	Not Connect.
17	VCOML_C3	Not Connect.
18	GVDD_C4	Not Connect.
19	VCL_C5	VCL pad. Place a 1uF/10V capacitor to GND.
20	AVDD_C6	AVDD pad. Place a 1uF/10V capacitor to GND.
21	VCI1_C7	VCI1 pad. Place a 1uF/10V capacitor to GND.
22	C12N	Place a 1uF/10V capacitor between C12N and C12P.



Pin No.	Symbol	Function
23	C12P	Place a 1uF/10V capacitor between C12P and C12N.
24	C11N	Place a 1uF/10V capacitor between C11N and C11P.
25	C11P	Place a 1uF/10V capacitor between C11P and C11N.
26	VGL_C10_D1	VGH pad. Place a 1uF/25V capacitor to GND.
27	VGH_C11	VGL pad. Place a 1uF/25V capacitor to GND.
28	C21N	Place a 1uF/10V capacitor between C21N and C21P.
29	C21P	Place a 1uF/10V capacitor between C21P and C21N.
30	C22N	Place a 1uF/25V capacitor between C22N and C22P.
31	C22P	Place a 1uF/25V capacitor between C22P and C22N.
32	C31N	Place a 1uF/25V capacitor between C31N and C31P.
33	C31P	Place a 1uF/25V capacitor between C31P and C31N.
34	LEDA	Power supply for LED Backlight Anode input.
35	LEDK1	Power supply for LED Backlight Cathode input.
36	LEDK2	Power supply for LED Backlight Cathode input.
37	LEDK3	Power supply for LED Backlight Cathode input.
38	VDD	Power supply.(2.8V) .



2.2.1 Application Notes:





2.2.2 Refer Initial code:

```
//Initial-----
void Initial Main(void)
                                      // For ILI9341
{
   WriteCOM Main(0xCF);
   WriteDAT_Main(0x00);
   WriteDAT_Main(0xD9);
   WriteDAT_Main(0x30);
   WriteCOM_Main(0xED);
   WriteDAT_Main(0x64);
   WriteDAT_Main(0x03);
   WriteDAT_Main(0x12);
   WriteDAT_Main(0x81);
   WriteCOM_Main(0xE8);
   WriteDAT_Main(0x85);
   WriteDAT_Main(0x00);
   WriteDAT_Main(0x78);
   WriteCOM_Main(0xCB);
   WriteDAT_Main(0x39);
   WriteDAT_Main(0x2C);
   WriteDAT_Main(0x00);
   WriteDAT_Main(0x34);
   WriteDAT_Main(0x02);
```



```
WriteCOM_Main(0xF7);
WriteDAT Main(0x20);
WriteCOM Main(0xEA);
WriteDAT_Main(0x00);
WriteDAT_Main(0x00);
WriteCOM_Main(0xC0);//Power control
WriteDAT_Main(0x21);//VRH[5:0] //0x1B
WriteCOM_Main(0xC1);//Power control
WriteDAT_Main(0x12);//SAP[2:0];BT[3:0]
WriteCOM_Main(0xC5); //VCOM Control
WriteDAT_Main(0x32);
WriteDAT_Main(0x3C);
WriteCOM_Main(0xC7); //VCOM Control2
WriteDAT_Main(0xa3); //0x9D
WriteCOM_Main(0x36); //Memory access Control
WriteDAT_Main(0x08);
WriteCOM_Main(0x3A); //Memory access Control
WriteDAT Main(0x55);
```



WriteCOM_Main(0xB1); WriteDAT_Main(0x00); WriteDAT_Main(0x1B); WriteCOM_Main(0xB6); //Display Function WriteDAT_Main(0x0a); WriteDAT_Main(0xa2); WriteCOM_Main(0xF6); WriteDAT_Main(0x01); WriteDAT_Main(0x30); WriteCOM_Main(0xF2); //3Gamma Function Disable WriteDAT_Main(0x00); WriteCOM_Main(0x26); //Gamma Curve select WriteDAT_Main(0x01); //----set gamma-



```
WriteCOM_Main(0xe0); //set gamma
WriteDAT_Main(0x0f);
WriteDAT_Main(0x1c);
WriteDAT_Main(0x19);
WriteDAT Main(0x08);
WriteDAT_Main(0x0b);
WriteDAT_Main(0x04);
WriteDAT_Main(0x4b);
WriteDAT_Main(0x64);
WriteDAT_Main(0x3e);
WriteDAT_Main(0x09);
WriteDAT_Main(0x15);
WriteDAT_Main(0x08);
WriteDAT_Main(0x16);
WriteDAT_Main(0x0D);
WriteDAT_Main(0x04);
WriteCOM_Main(0xe1); //set gamma
WriteDAT_Main(0x00);
WriteDAT_Main(0x1a);
WriteDAT_Main(0x1e);
WriteDAT_Main(0x03);
WriteDAT_Main(0x0f);
WriteDAT_Main(0x03);
WriteDAT_Main(0x35);
WriteDAT_Main(0x23);
```



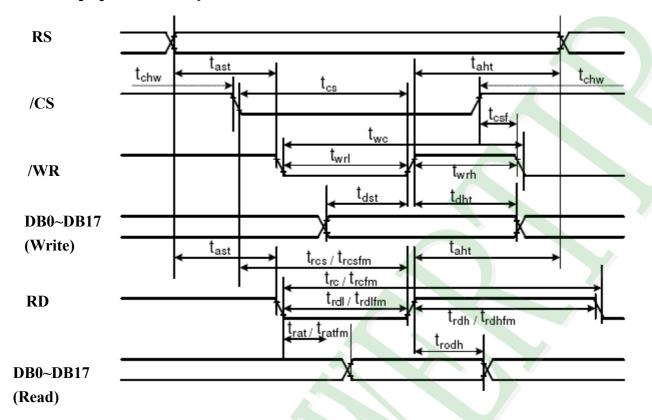
WriteDAT_Main(0x45);
WriteDAT_Main(0x04);
WriteDAT_Main(0x0c);
WriteDAT_Main(0x0b);
WriteDAT_Main(0x2b);
WriteDAT_Main(0x2e);
WriteDAT_Main(0x05);
WriteCOM_Main(0x11); //exit sleep
Delay(120);
WriteCOM_Main(0x29);//Display on

}



2.3 Timing Characteristics

80-Sysyem Bus Operation



VDD= 2.8V, Ta=25°C

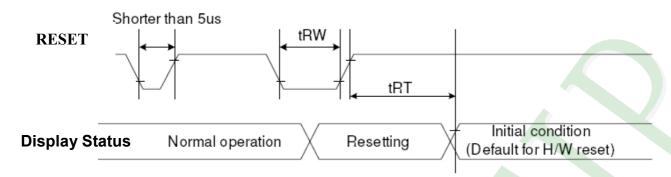
			V	DD- 2.0 v	, Id-25 C
Signal	Symbol	Parameter	Min	Max	Unit
RS	tast	Address Setup time	0	-	ns
	taht	Address Hold time(Write/Read)	0	-	ns
	tCHW	CS "H" pulse width	0	-	ns
	tCS	Chip select Setup time (Write)	15	-	
/CS	trcs	Chip Select setup time (Read ID)	45		
	trcsfm	Chip select Setup time (Read FM)	355	-	ns
	tCSF	Chip select wait time(Write/Read)	10	-	ns
	tWC	Write Cycle	66	-	ns
WR	tWRH	Control pulse "H" duration	15	-	ns
	tWRL	Control pulse "L" duration	15	-	ns
	tRCFM	Read Cycle(FM)	450	-	ns
RD(FM)	tRDHFM	Read Control H duration (FM)	90	-	ns
	tRDLFM	Read Control L duration (FM)	355	-	ns



	trc	Read Cycle(ID)	160		ns
RD(ID)	trdh	Read Control pulse H duration	90		ns
	trdl	Read Control pulse L duration			ns
	tDST	Write Data setup time	10		ns
DB0~DB17 tDHT		Write Data hold time	10		ns
	tRAT	Read access time		40	ns
	tRATFM	Read access time	_	340	ns
	tODH	Read Output disable time	20	80	ns



LCD Reset

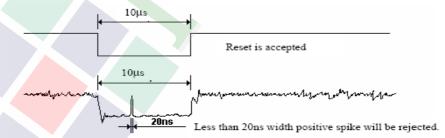


Signal	Symbol	Parameter	Min.	Max.	Unit
	tRW	Reset pulse duration	10	-	us
	4DT	Deset sensel	-	5 (Note1,5)	ms
	tRT	Reset cancel		120 (Note1,6,7)	ms

- Note 1: The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NV memory to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5 ms after a rising edge of RESX.
- Note 2: Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below: -

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 10us	Reset
Between 5us and 10us	Reset starts

- Note 3: During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In -mode.) And then return to Default condition for Hardware Reset.
- Note 4: Spike Rejection also applies during a valid reset pulse as shown below:

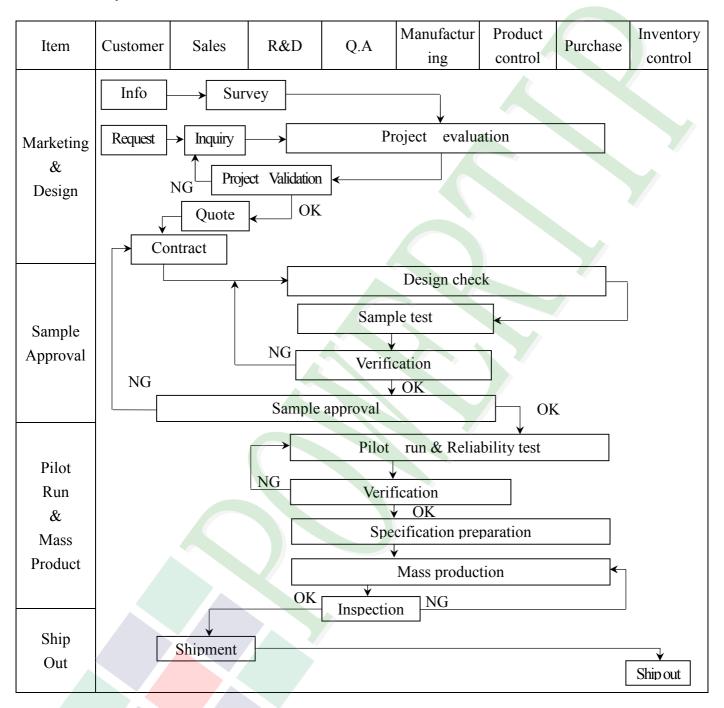


- Note 5: When Reset applied during Sleep In Mode.
- Note 6: When Reset applied during Sleep Out Mode.
- Note 7: It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.

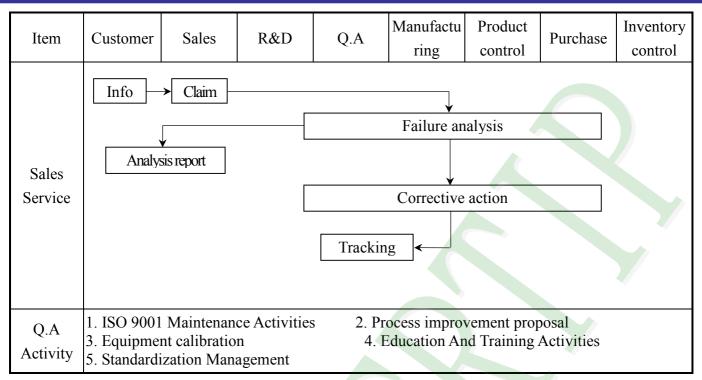


3. QUALITY ASSURANCE SYSTEM

3.1 Quality Assurance Flow Chart



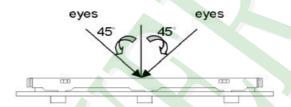




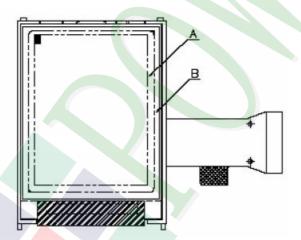


3.2. Inspection Specification

- ◆Scope : The document shall be applied to TFT-LCD Module for less than 3, 5" (Ver.B01).
- ◆Inspection Standard: MIL-STD-105E Table Normal Inspection Single Sampling Level Ⅱ.
- ◆Equipment: Gauge、MIL-STD、Powertip Tester、Sample
- ◆Defect Level: Major Defect AQL: 0,4; Minor Defect AQL: 1,5
- **♦**OUT Going Defect Level: Sampling.
- ◆Standard of the product appearance test:
 - a. Manner of appearance test:
 - (1). The test best be under 20W×2 fluorescent light, and distance of view must be at 30 cm.
 - (2). The test direction is base on about around 45° of vertical line.



(3). Definition of area.



A area: viewing area

B area: Outside of viewing area

(4). Standard of inspection: (Unit: mm)



\spadesuit Specification For TFT-LCD Module Less Than 3. 5" :

¥ 1	Specification 101 111 EeD Module Less Than 0, 0					(101.001)
NO	Item			Criterio	on	Level
		1	e part nu roduction	ımber is inconsistent ı.	with work order of	Major
01	Product condition	1. 2 Mi	1. 2 Mixed product types.			Major
			sembled	in inverse direction.		Major
02	Quantity	2. 1Th	e quantit	y is inconsistent with	ı work order of productio	on. Major
03	Outline dimension		3. 1 Product dimension and structure must conform to structure diagram.			cture Major
			issing lin	e character and icon		Major
		4. 2 No	4. 2 No function or no display.			Major
04	Electrical Testing	4. 3 Display malfunction.			Major	
		4. 4 LCD viewing angle defect.			Major	
		4. 5 Cu	irrent co	nsumption exceeds p	roduct specifications.	Major
				Item	Acceptance (Q'ty)	
	Dot defect			Bright Dot	≦ 2	
			Dot	Dark Dot	≦ 3	
05	(Bright dot \		Defect	Joint Dot	≦ 2	
	Dark dot)			Total	≦ 3	Minor
		5. 1 In	spection	pattern: full white	, full black , Red , Green	n and
	On -display			blue screen	ıs.	
		5. 2 It i	is defined	d as dot defect if defe	ect area $>1/2$ dot.	
		5. 3 Th	e distan	e between two dot d	efect ≧5 mm.	



♦ Specification For TFT-LCD Module Less Than 3.5":

_		viodule Less Than 5.5			Level
NO	Item	Cri	Criterion		
		6. 1 Round type (Non-display	or display):		
		Dimension	Acceptance	e (Q'ty)	
	Disabassanhita	(diameter ÷ Φ)	A area	B area	
	Black or white dot \ scratch \	$\Phi \le 0.15$	Ignore		
	contamination	$0.15 < \Phi \leq 0.20$	2		
	Round type	$0.20 \ < \ \Phi \leq 0.30$	2	Ignore	
	→ <u>x</u> ← ↓	$\Phi > 0.30$	0		
06	<u> </u>	Total	3		Minor
	$\Phi = (x+y)/2$	6. 2 Line type(Non-display or	display) :		, and
	Line type	Dimension	Accepta	nce (Q'ty)	
	Line type ↓	Length (L) Width (W)) A area	B area	
	Ţ † W	W ≤ 0	0.03 Ignore		
	→ _L	$L \le 5.0 \qquad 0.03 < W \le 0$.05 3		
		W >0	0.05 As round type	l Ignore	
		Total	3		
		Dimension	Acceptance	(Q'ty)	
		(diameter : Φ)	A area	B area	
	Polarizer	$\Phi \leq 0.20$	Ignore		
07	Bubble	$0.20 < \Phi \leq 0.50$	3	Ignore	Minor
		$\Phi > 0.50$	0	Ignore	
		Total	3		



lacktriangle Specification For TFT-LCD Module Less Than 3.5":

NO	Item	Criterion		Level
		Z : The thickness of crack	Y : The width of crack. W : terminal length a : LCD side length	
		8.1 General glass chip: 8.1.1 Chip on panel surface and cra	ack between panels:	
		Y Z	Z Y Y	
08	The crack of glass	SP Y [OK]	SP [NG]	Minor
		Seal width Z	Y	
		X Y	z	
		≤ a Crack can't enter viewing area	≦1/2 t	
		≤ a Crack can't exceed the half of SP width.	1/2 t < Z ≤2 t	



◆Specification For TFT-LCD Module Less Than 3, 5":

NO	Item	Criterion	Level
		Symbols: X: The length of crack Z: The thickness of crack t: The thickness of glass 8. 1. 2 Corner crack:	
		$egin{array}{ c c c c c c c c c c c c c c c c c c c$	
08	The crack of glass	$\leq 1/5$ a Crack can't exceed the half of SP width. $1/2$ t $<$ Z ≤ 2 t	Minor
00	The crack of glass	8.2 Protrusion over terminal:	MINIO
		8. 2. 1 Chip on electrode pad: W Y W Y W Y X W Y X Y Z	
	X	X	
		$ \begin{array}{c cccc} X & Y & Z \\ \hline Front & \leq a & \leq 1/2 W & \leq t \\ \end{array} $	
		Back \leq a \leq W \leq 1/2 t	



◆Specification For TFT-LCD Module Less Than 3.5″:

	Symbols: X: The length of crack Z: The thickness of crack t: The thickness of glass 8. 2. 2 Non-conductive portion: W X Y X Y Z X Y X Y Z	
The crack of glass	 ≤ 1/3 a ≤ W ≤ t ⊙ If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. 8. 2. 3 Glass remain : 	Minor
	8. 2. 3 Glass remain:	
	50 5 - C. (10 - C)))))))))))))))))))))))))))))))))))	The crack of glass



lacktriangle Specification For TFT-LCD Module Less Than 3. 5":

NO	Item	Criterion	Level
		9, 1 Backlight can't work normally.	Major
09	Backlight elements	9. 2 Backlight doesn't light or color is wrong.	Major
		9. 3 Illumination source flickers when lit.	Major
	diagram. 10. 2 No short circuits in components on PCB or FP 10. 3 Parts on PCB or FPC must be the same as on characteristic chart .There should be no missing parts or excess parts. General appearance 10. 4 Product packaging must the same as specified specification sheet. 10. 5 The folding and peeled off in polarizer are not	10. 1 Pin type `quantity `dimension must match type in structure diagram.	Major
		10. 2 No short circuits in components on PCB or FPC .	Major
10		10. 3 Parts on PCB or FPC must be the same as on the production characteristic chart .There should be no wrong parts , missing parts or excess parts.	Major
10		10. 4 Product packaging must the same as specified on packaging specification sheet.	Minor
		10. 5 The folding and peeled off in polarizer are not acceptable.	Minor
		10. 6 The PCB or FPC between B/L assembled distance(PCB or FPC) is ≤ 1.5 mm.	Minor



4. RELIABILITY TEST

4. 1 Reliability Test Condition

NO.	TEST ITEM	TES	TEST CONDITION		
1	High Temperature Storage Test	Keep in +80 ±2°C 96 hrs Surrounding temperature, then storage at normal condition 4hrs.			
2	Low Temperature Storage Test	Keep in - 30 ±2°C 96 hrs Surrounding temperature, t	Keep in - 30 ±2°C 96 hrs Surrounding temperature, then storage at normal condition 4hrs.		
3	High Temperature / High Humidity Storage Test	Keep in +60°C /90% R.H duration for 96 hrs Surrounding temperature, then storage at normal condition 4hrs. (Excluding the polarizer)			
		Air Discharge: Apply 2 KV with 5 times Discharge for each polarity	Contact Discharge: Apply 250V with 5 times discharge for each polarity +/-		
4	ESD Test	 Temperature ambiance:15°C ~35°C Humidity relative:30% ~60% Energy Storage Capacitance(Cs+Cd):150pF±10% Discharge Resistance(Rd):330Ω±10% Discharge, mode of operation: Single Discharge (time between successive discharges at least 1 s) (Tolerance if the output voltage indication: ±5%) 			
5	Temperature Cycling Storage Test	$\begin{array}{cccccccccccccccccccccccccccccccccccc$			
6	Vibration Test (Packaged)	 Sine wave 10~55 Hz frequency (1 min) The amplitude of vibration :1. 5 mm Each direction (X \ Y \ Z) duration for 2 Hrs 			
		Packing Weight	nt (Kg) Drop Height (cm)		
		0 ~ 45	5. 4 122		
7	Drop Test	45. 4 ~ 90			
'	(Packa <mark>ged)</mark>	90.8 ~ 45			
		Over 454	4 46		
		Drop direction: ※ 1 corn	ner / 3 edges / 6 sides each 1times		



5. PRECAUTION RELATING PRODUCT HANDLING

5.1 SAFETY

- 5.1.1 If the LCD panel breaks, be careful not to get the liquid crystal to touch your skin.
- 5.1.2 If the liquid crystal touches your skin or clothes, please wash it off immediately by using soap and water.

5.2 HANDLING

- 5.2.1 Avoid any strong mechanical shock which can break the glass.
- 5.2.2 Avoid static electricity which can damage the CMOS LSI—When working with the module, be sure to ground your body and any electrical equipment you may be using.
- 5.2.3 Do not remove the panel or frame from the module.
- 5.2.4 The polarizing plate of the display is very fragile. So , please handle it very carefully ,do not touch , push or rub the exposed polarizing with anything harder than an HB pencil lead (glass , tweezers , etc.)
- 5.2.5 Do not wipe the polarizing plate with a dry cloth, as it may easily scratch the surface of plate.
- 5.2.6 Do not touch the display area with bare hands, this will stain the display area.
- 5.2.7 Do not use ketonics solvent & aromatic solvent. Use with a soft cloth soaked with a cleaning naphtha solvent.
- 5.2.8 To control temperature and time of soldering is 320±10°C and 3-5 sec.
- 5.2.9 To avoid liquid (include organic solvent) stained on LCM.

5.3 STORAGE

- 5.3.1 Store the panel or module in a dark place where the temperature is 25° C $\pm 5^{\circ}$ C and the humidity is below 65% RH.
- 5.3.2 Do not place the module near organics solvents or corrosive gases.
- 5.3.3 Do not crush, shake, or jolt the module.

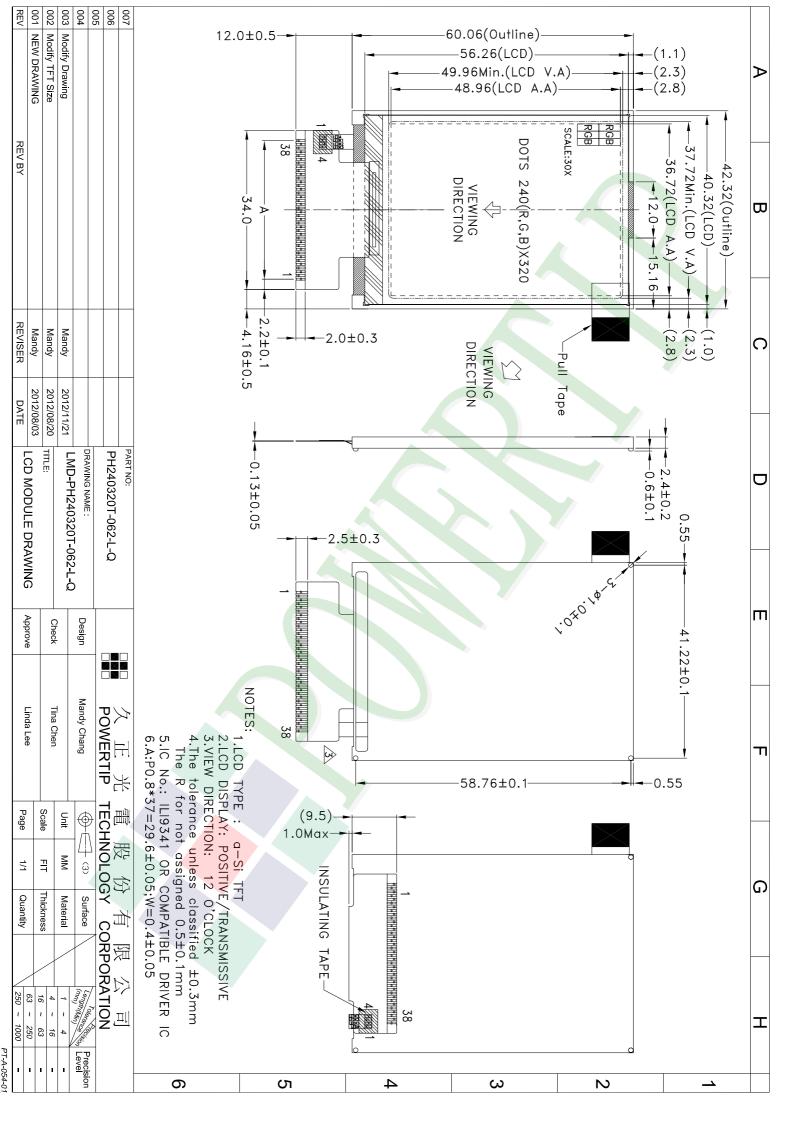
5.4 TERMS OF WARRANTY

5.4.1 Applicable warrant period

The period is within Twenty-four months since the date of shipping out under normal using and storage conditions.

5.4.2 Unaccepted responsibility

This product has been manufactured to your company's specification as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other use apart from general electronic equipment, we cannot take responsibility if the product is used in nuclear power control equipment, aerospace equipment, fire and security systems or any other applications in which there is a direct risk to human life and where extremely high levels of reliability are required.



Ver.001 Documents NO. PKG-PH240320T-062-L-Q

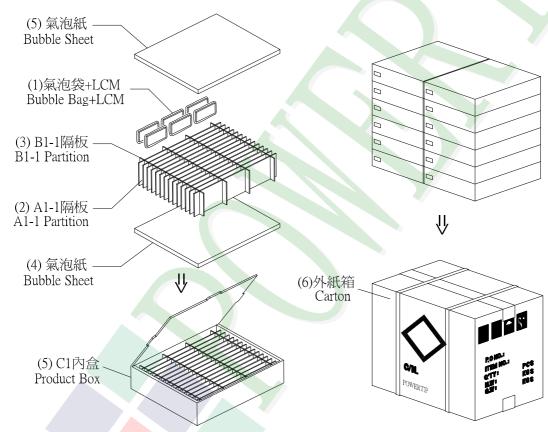
LCM包裝規格書 LCM Packaging Specifications

Approve	Check	Contact
Linda Lee	Tina Chen	Mandy Chang

1.包裝材料規格表 (Packaging Material): (per carton)

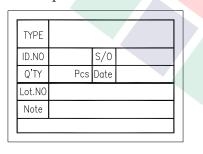
No.	Item	Model	Dimensions (mm)	1Pcs Weight	Quantity	Total Weight
1	成品 (LCM)	PH240320T-062-L-Q	42.32 X 60.06	0.0089	468	4.1652
2	氣泡袋(1)Bubble Bag	BAG100065BRABA	100 X 65	0.0008	468	0.3744
3	A1-1隔板(2)A1-1 Partition	BX29500047BZBA	295 X 47 X 3	0.0078	96	0.7488
4	B1-1隔板(3)B1-1 Partition	BX24500047BZBA	245 X 47 X 3	0.0065	48	0.312
5	氣泡紙(4)Bubble Sheet	BAG280240BWABA	280 X 240	0.006	24	0.144
6	C1內盒(5)Product Box	BX31025555AABA	310 X 255 X 55	0.13	12	1.56
7	外紙箱(6)Carton	BX52732536CCBA	527 X 325 X 360	0.83	1	0.83
8						
9						

- 2.一 整箱總重量 (Total LCD Weight in carton):
- 3.單箱數量規格表 (Packaging Specifications and Quantity):
 - (1)Quantity Of Spacer: A1-1隔板 X 8 , B1-1隔板 X
- (2) Total LCM quantity in carton: quantity per box x no of boxes 468



特 記 項 (REMARK)

4. Label Specifications:



參照"成品包裝點檢作業標準書"內容

- 5. LCM排放示意圖(前後間隔不放置):
- 5. LCM placed as figure showing: (First and last slot should be empty)



☑ 模組(LCM) X 2pcs. 模組(LCM) X 1pcs.

- 6. 最外格所放之產品,玻璃面要朝向內側.
- 6. Put in the outermost cell products, glass surface toward the inside.